

Trouble Response Playbook (Tier-1/Tier-2)

Revision: 3.0
Date: 2025-10-08
Company: ACME Lithography Systems

Disclaimer: This is a fictional internal document created for demo purposes. Any resemblance to real products or specifications is coincidental.

Revision History

Version	Date	Author	Summary
3.0	2025-10-08	Manufacturing Engineering	Periodic update; limits & procedures clarified.

Table of Contents

§TR-1 — Pre-Check Failures

§TR-2 — Dose Drift

§TR-3 — Overlay Residual High (Y-dominant)

§TR-4 — Focus Map Tilt

§TR-1 Pre-Check Failures

If interlocks not green → stop; escalate to Tier-2 if unresolved in 10 min.

§TR-2 Dose Drift

Localized drift → check pupil clipping; sensor recal; global drift → verify source ripple & PFN caps.

§TR-3 Overlay Residual High (Y-dominant)

Inspect reticle chuck flatness; run stage thermal comp; if residual persists > 3.5 nm, schedule chuck re-seat.

§TR-4 Focus Map Tilt

Verify wafer clamping and stage leveling; run BF re-map; if tilt > 8 nm across field, Tier-2.

Appendices & Tables

Table A.1: Decision Tree Snippets

Symptom	Check	If yes →	If no →
Dose localized drift	Pupil clipping	Adjust pupil; re-run D25	Recal dose sensor
Overlay Y high	Chuck warp signs	Re-seat chuck	Thermal comp routine
Focus tilt	Stage level drift	Leveling routine	Clamp check